Schottky Barrier Diode

DB2441600L

### **Panasonic**

### DB2441600L

### Silicon epitaxial planar type

### For rectification

#### ■ Features

- · Low forward voltage VF
- Forward current (Average) IF(AV) = 3 A rectification is possible
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: 4P

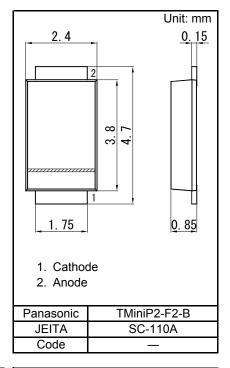
Established: 2010-03-01

: 2013-04-19

Revised

#### ■ Packaging

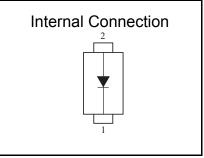
Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)



### ■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Reverse voltage	VR	40	V
Forward current (Average) *1	IF(AV)	3.0	Α
Non-repetitive peak forward surge current *2	IFSM	50	Α
Junction temperature	Tj	125	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +125	°C

Note: \*1 For embedded alumina substrate (substrate size: 5 cm× 5 cm)



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<sup>\*2 50</sup> Hz sine wave 1 cycle (Non-repetitive peak current)

Revision. 3

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### ■ Electrical Characteristics Ta = 25 °C ± 3 °C

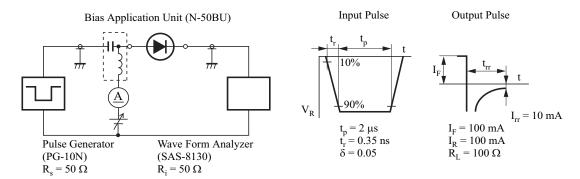
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	IF = 3.0 A		0.40	0.45	V
Reverse current	IR	VR = 40 V		60	300	μA
Terminal capacitance	Ct	VR = 10 V, f = 1 MHz		95		pF
Reverse recovery time *1	trr	IF = IR = 100 mA Irr = 10 mA, RL = 100 $\Omega$		30		ns

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
  - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
  - 3. \*1 trr test circuit

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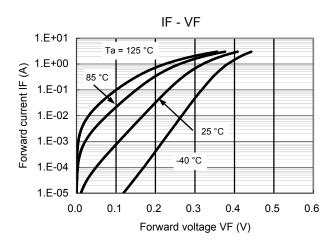


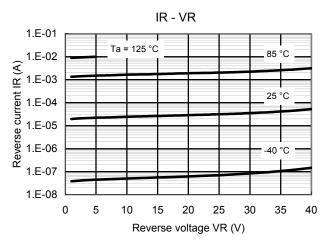
Schottky Barrier Diode

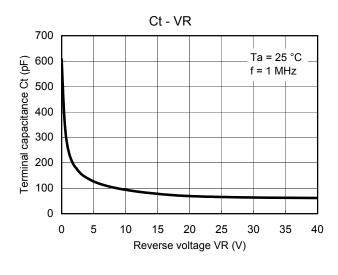
DB2441600L

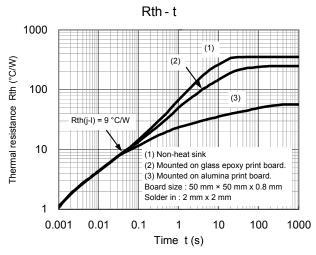
### **Panasonic**

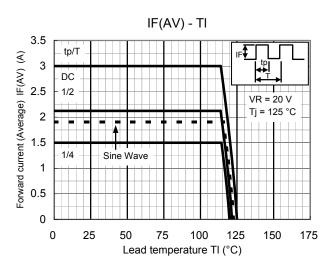
### Technical Data (reference)

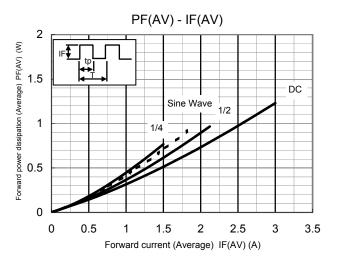












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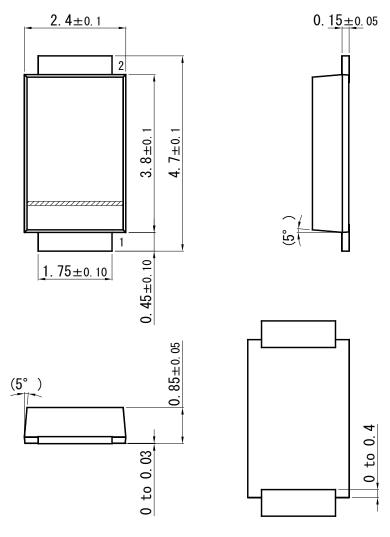
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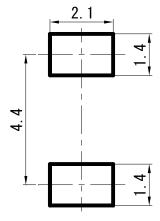
TMiniP2-F2-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)

Established: 2010-03-01 Revised: 2013-04-19



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